

50A, 60V, N-Channel MOSFET

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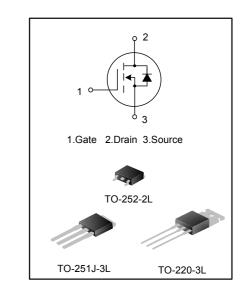
General Description

The GGVD50N06T is an N-channel enhancement mode high voltage MOS field effect transistor. An improved planar stripe cell and improved guard ring terminal have been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulses in the avalanche and commutation modes.

Features

- 50A, 60V
- $R_{DS(on)}$ (typ) =18m Ω @V_{GS}=10V
- Low gate charge
- Low Crss
- Fast switching
- Improved dv/dt capability

Nomenclature



Applications

- Electronic Ballasts
- Low Power SMPS

N denotes N Channel

Package information. — Example:T:TO-220; D:TO-252; MJ:TO-251J. Nominal Voltage,using 2 digits

Example: 60 denotes 600V, 65 denotes 650V.

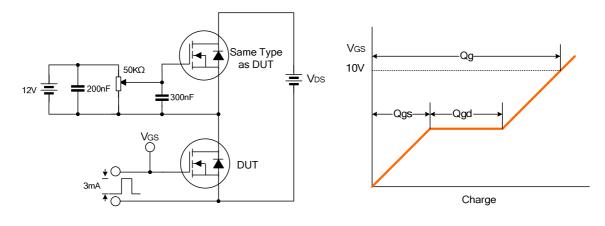
Special Features indication, May be omitted. Example: E denotes embeded ESD structure

Ordering Information

Part No.	Package	Marking	Material	Packing
GGVD50N06T	TO-220-3L	GGVD50N06T	Pb free	Tube
GGVD50N06D	TO-252-2L	GGVD50N06D	Pb free	Tube
GGVD50N06DTR	TO-252-2L	GGVD50N06D	Pb free	Tape & Reel
GGVD50N06MJ	TO-251J-3L	GGVD50N06MJ	Pb free	Tube

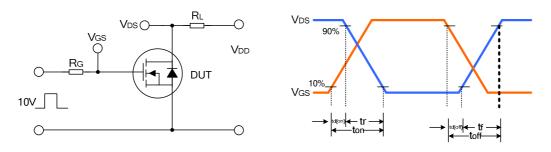


Typical Test Circuits

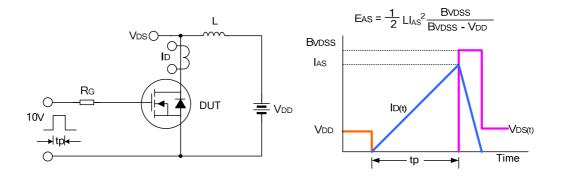


Gate Charge Test Circuit & Waveform

Resistive Switching Test Circuit & Waveform

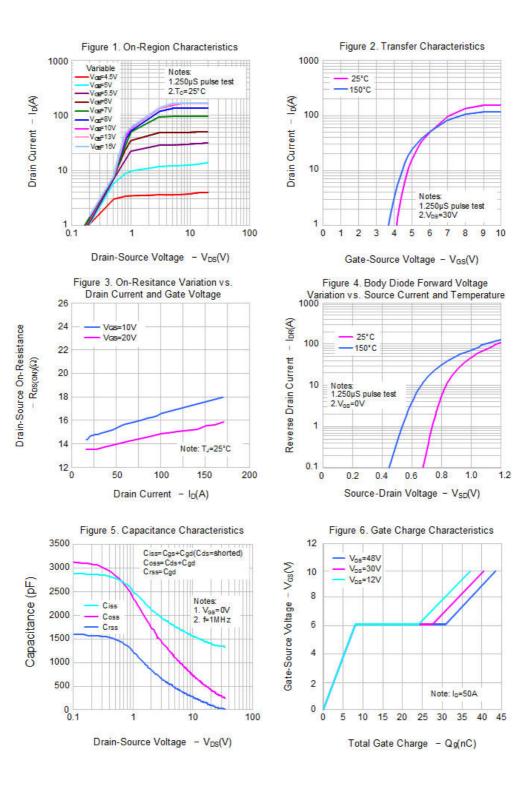


Unclamped Inductive Switching Test Circuit & Waveform





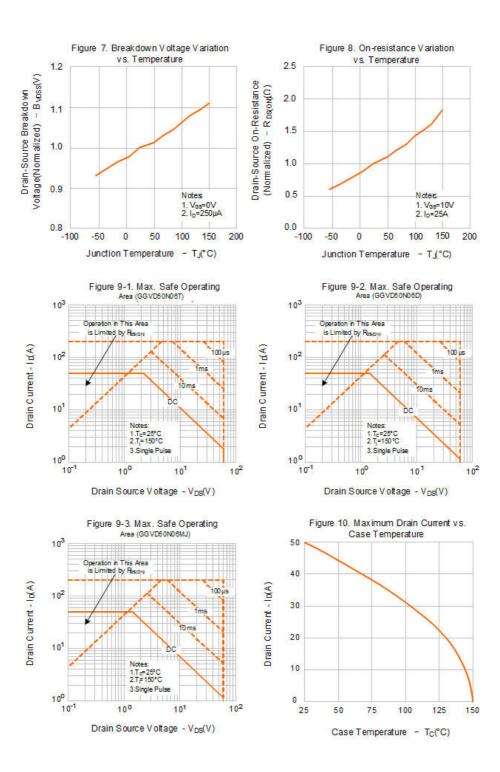
Typical Characteristics



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Absolute Maximum Ratings (Tc=25°C unless otherwise noted)

Characteristics		Symbol	Rating			
			GGVD50N06T	GGVD50N06D	GGVD50N06MJ	Unit
Drain-Source Voltage		V _{DS}		V		
Gate-Source Voltage		V_{GS}		V		
Durain Quarter (T _C =25°C	I _D	50			
Drain Current	T _c =100°C		31.62			
Drain Current Pulsed		I _{DM}		А		
Power Dissipation(T _c =25°C)			110	72	83	W
-Derate above 25°C		P _D	0.88	0.58	0.66	W/°C
Single Pulsed Avalanche Energy(Note 1)		E _{AS}	272			
Operation Junction Temperature Range		TJ	-55~+150			
Storage Temperature Range		T _{stg}	-55~+150			

Thermal Characteristics

	Symbol	Rating			
Characteristics		GGVD50N06T	GGVD50N06D	GGVD50N06MJ	Unit
Thermal Resistance, Junction-to-Case	$R_{ extsf{ heta}JC}$	1.14	1.74	1.51	°C/W
Thermal Resistance, Junction-to-Ambient	$R_{ extsf{ heta}JA}$	62.50	110	110	°C/W

Electrical Characteristics (Tc=25°C, Unless Otherwise Specified

Characteristics	Symbol	Test conditions	Min.	Тур.	Max.	Unit	
Drain -Source Breakdown Voltage	B _{VDSS}	V _{GS} =0V, I _D =250µA	60			V	
Drain-Source Leakage Current	I _{DSS}	V _{DS} =60V, V _{GS} =0V			1.0	μA	
Gate-Source Leakage Current	I _{GSS}	$V_{GS}=\pm 20V, V_{DS}=0V$			±100	nA	
Gate Threshold Voltage	V _{GS(th)}	V_{GS} = V_{DS} , I_D =250 μ A	2.0		4.0	V	
Static Drain- Source On State Resistance	R _{DS(on)}	V_{GS} =10V, I_{D} =25A		18	23	mΩ	
Input Capacitance	C _{iss}			1375.8			
Output Capacitance	C _{oss}	$V_{DS}=25V, V_{GS}=0V,$		393.2		pF	
Reverse Transfer Capacitance	C _{rss}	f=1.0MHz		102.6			
Turn-on Delay Time	t _{d(on)}			21.67			
Turn-on Rise Time	t _r	V _{DD} =30V, R _G =25Ω		86.67			
Turn-off Delay Time	t _{d(off)}	I _D =50A		32.33		ns	
Turn-off Fall Time	t _f			93			
Total Gate Charge	Q_g			43.25			
Gate-Source Charge Q _{gs}		V_{DS} =48V, I _D =50A,		8.11		nC	
Gate-Drain Charge	Q_{gd}	V _{GS} =10V		23.76			
Gate resistance	R_{G}	f=1MHz, Drain Open, OSC Level: 20mv		2.2		Ω	



Source-Drain Diode Ratings and Characteristics

Characteristics	Symbol	Test conditions	Min.	Тур.	Max.	Unit
Continuous Source Current	I _s	Integral Reverse P-N			50	
Pulsed Source Current	I _{SM}	Junction Diode in the MOSFET	-		200	A
Diode Forward Voltage	V_{SD}	I _S =50A, V _{GS} =0V			1.2	V
Reverse Recovery Time	T _{rr}	I _S =50A, V _{GS} =0V,		67.2		ns
Reverse Recovery Charge	Q _{rr}	dI _F /dt=100A/µs		0.2		μC

Notes:

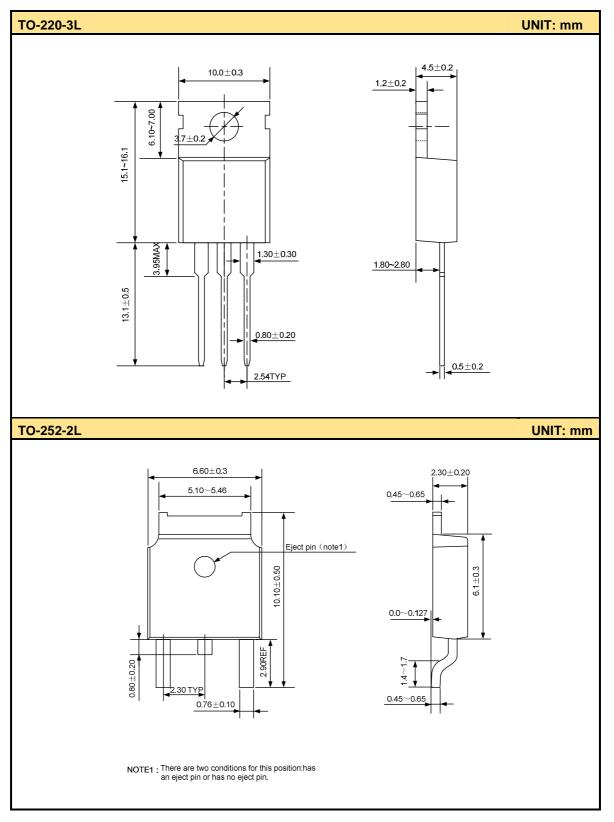
1. L=0.1mH, IAS=53A, V_{DD}=35V, RG=20 Ω , starting T_J=25°C;

- 2. Pulse Test: Pulse width ≤300µs,Duty cycle≤2%;
- 3. Essentially independent of operating temperature.

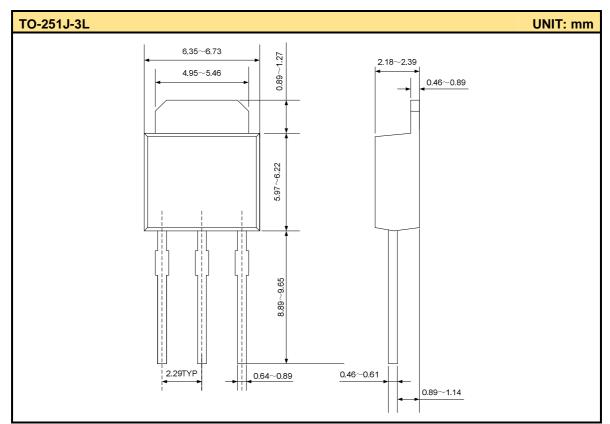


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Package Outline







Package Outline (continued)

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